

U.S. PTO
10/087432
03/01/02

U.S. UTILITY Patent Application

PATENT NUMBER and
ISSUE DATE

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10087432	03/01/2002	257	177	2811	Michael

**APPLICANTS: Wang Sung-Fei; Pai Tsung-Ming; Chen Kuang-Hui;

**CONTINUING DATA VERIFIED:

** FOREIGN APPLICATIONS VERIFIED:

TAIWAN 90104 '84 03/01/2001

PG-PUB ☐ DO NOT PUBLISH ☐

RESCIND ☐

Foreign priority claimed ☐ yes ☐ no
35 USC 119 conditions met ☐ yes ☐ no

ATTORNEY DOCKET NO

U 013887-9

TITLE : Stacked semiconductor chip package

U.S. DEPT. OF COMM./PAT. & TM.-PTO-436L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED

ISSUE FEE

Amount Due Date Paid

☐ TERMINAL
DISCLAIMER

Assistant Examiner

Primary Examiner

PREPARED FOR ISSUE

CLAIMS ALLOWED

Total Claims Print Claim for
O.G.

DRAWING

Sheets Drwg. Figs. Drwg. Print Fig.

2C

Application Examiner

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